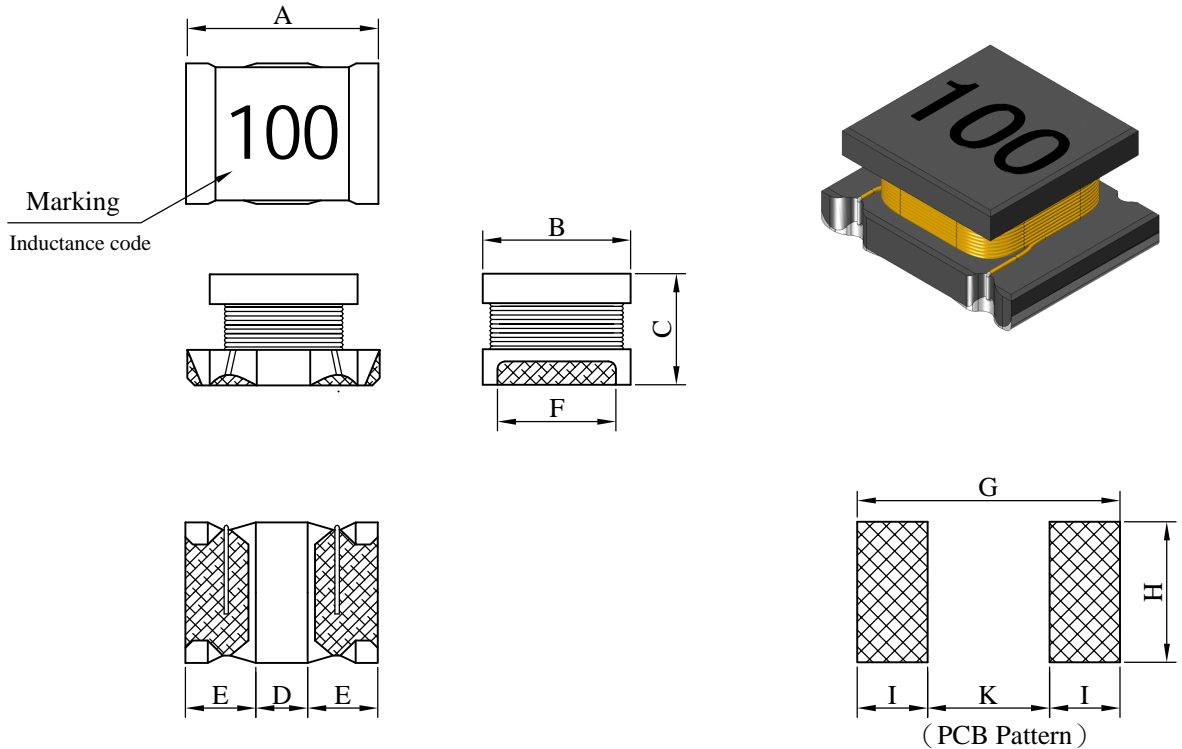


SPECIFICATION FOR APPROVAL

REF. :

| | | | | | |
|------------|--------------------|---------------|------------------|------|---|
| PROD. NAME | SMD Power Inductor | ABC'S DWG NO. | SQ3226□□□□L□-□□□ | | |
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I . Configuration and dimensions :



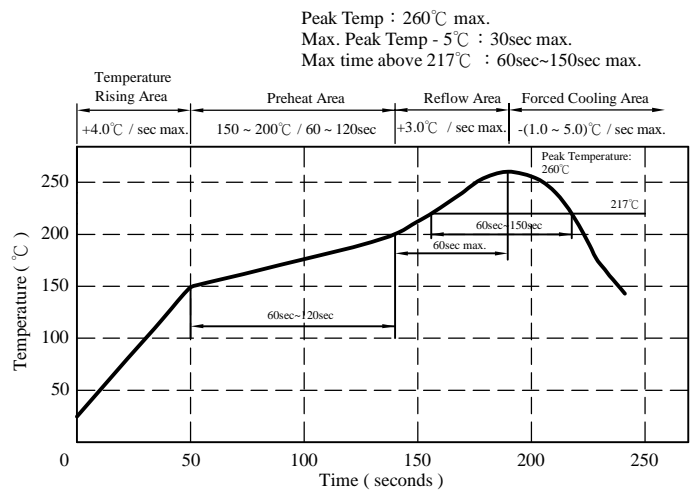
| A | B | C | D | E | F | G | H | I | K |
|-----------|-----------|------------|-----------|-----------|-----------|-----------|-----------|-----------|-----------|
| 3.20 ±0.3 | 2.50 ±0.3 | 1.55 ±0.15 | 1.30 typ. | 1.20 ref. | 1.20 ref. | 3.80 ref. | 2.80 ref. | 1.40 ref. | 1.00 ref. |

II . Description :

- a . Ferrite drum core construction.
- b . Enamelled copper wire : F class
- c . Product weight : 0.042g (ref.)
- d . Moisture sensitivity Level 1
- e . Products comply with RoHS' requirements
- f . Halogen free available

III . General specification :

- a . Storage temp. : -40°C ----+125°C
- b . Operating temp. : -40°C ----+125°C
(Temp. rise included)
- c . Resistance to solder heat : 260°C .10 secs.



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SPECIFICATION FOR APPROVAL

REF. :

| | | | | | |
|------------|--------------------|---------------|------------------|------|---|
| PROD. NAME | SMD Power Inductor | ABC'S DWG NO. | SQ3226□□□□L□-□□□ | | |
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IV . Electrical characteristics :

| DWG No. | Inductance (μ H) | SRF (MHz) min. | RDC (Ω) max. | IDC (mA) |
|------------------|--------------------------|----------------------|-----------------------------|-------------|
| SQ32261R0ML□-□□□ | 1.0 \pm 20% | 100.0 | 0.078 | 1000 |
| SQ32262R2ML□-□□□ | 2.2 \pm 20% | 63.0 | 0.126 | 790 |
| SQ32264R7ML□-□□□ | 4.7 \pm 20% | 43.0 | 0.195 | 650 |
| SQ32266R8ML□-□□□ | 6.8 \pm 20% | 32.0 | 0.325 | 540 |
| SQ3226100KL□-□□□ | 10.0 \pm 10% | 26.0 | 0.390 | 450 |
| SQ3226150KL□-□□□ | 15.0 \pm 10% | 26.0 | 0.754 | 300 |
| SQ3226220KL□-□□□ | 22.0 \pm 10% | 19.0 | 0.923 | 250 |
| SQ3226330KL□-□□□ | 33.0 \pm 10% | 17.0 | 1.430 | 200 |
| SQ3226470KL□-□□□ | 47.0 \pm 10% | 15.0 | 1.690 | 170 |
| SQ3226680KL□-□□□ | 68.0 \pm 10% | 12.0 | 2.860 | 130 |
| SQ3226101KL□-□□□ | 100.0 \pm 10% | 10.0 | 4.550 | 100 |

- 1). □ : Packaging information : □ Code
- 2). "- □□□ " : Reference code
- 3). Electrical specifications at 25°C
- 4). Inductance Test Freq. : 1MHz / 0.1V
- 5). IDC base on Temp. rise 20°C max. & Δ L / L0A=10% typ.

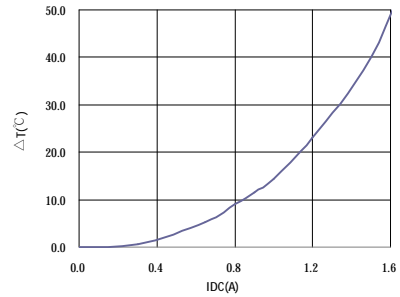
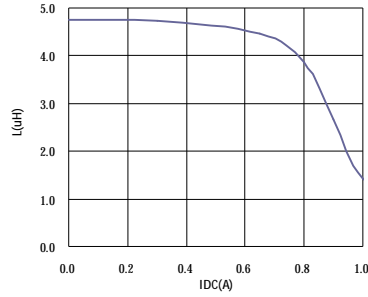
SPECIFICATION FOR APPROVAL

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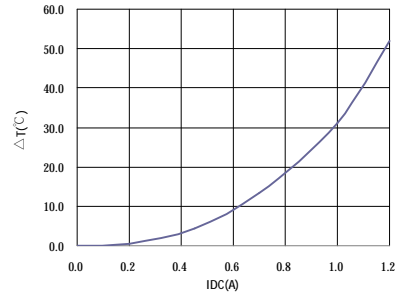
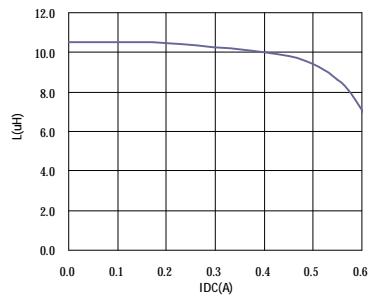
| | | | | | |
|---------------|--------------------|---------------|------------------|------|---|
| PROD. NAME | SMD Power Inductor | ABC'S DWG NO. | SQ3226□□□□L□-□□□ | | |
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V . Curve :

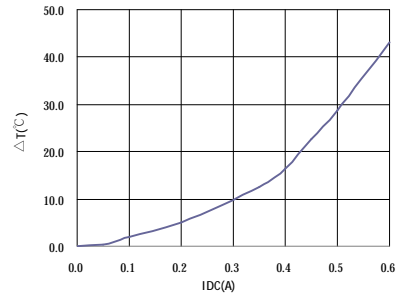
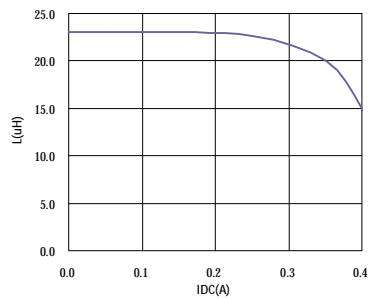
SQ32264R7ML□



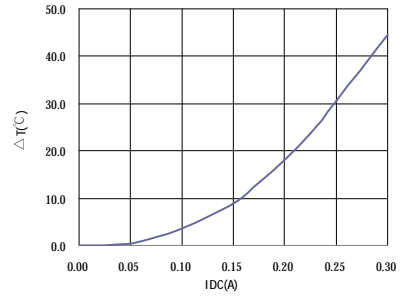
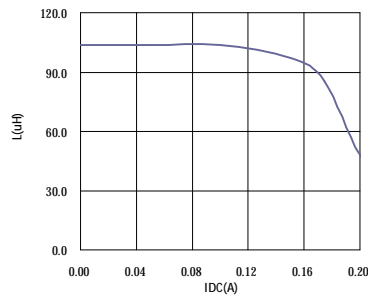
SQ3226100KL□



SQ3226220KL□



SQ3226101KL□



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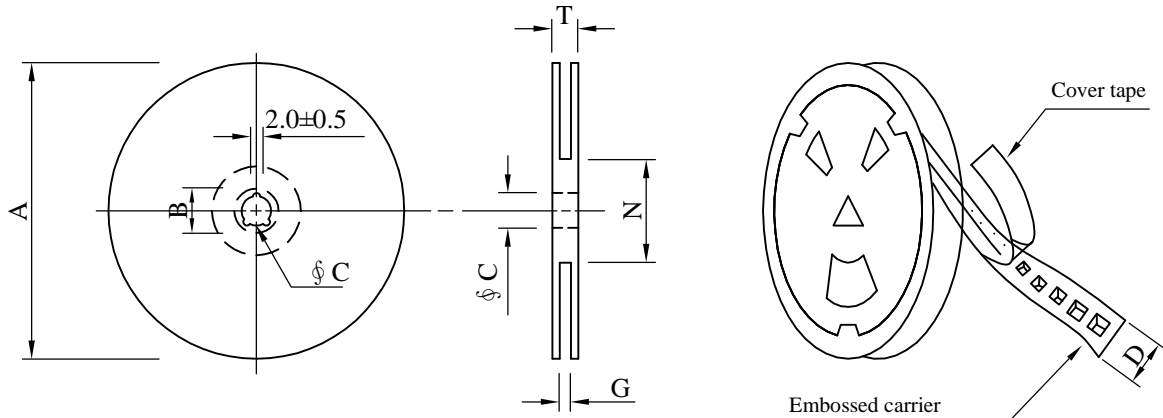
SPECIFICATION FOR APPROVAL

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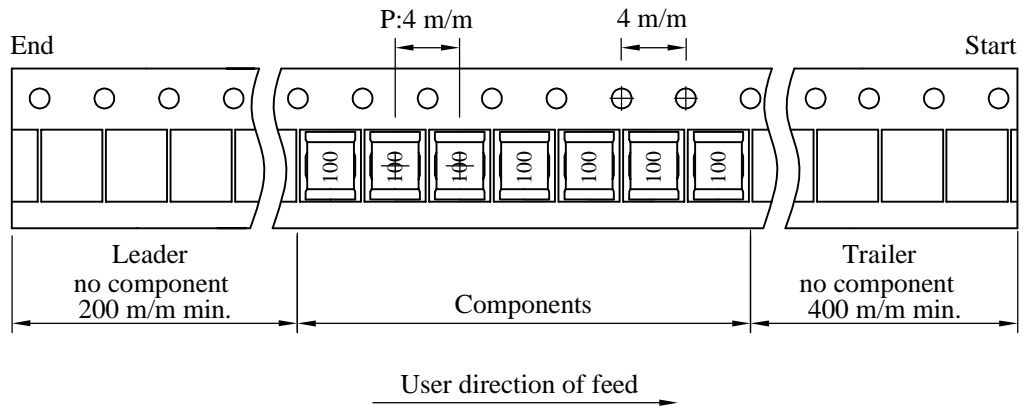
| | | | | | |
|------------|--------------------|---------------|------------------|------|---|
| PROD. NAME | SMD Power Inductor | ABC'S DWG NO. | SQ3226□□□□L□-□□□ | | |
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VI . Packaging information :

(1) Configuration



※Carrier tape width : D



(2) Dimensions

Unit:m/m

| Style | A | B | C | D | G | N | T |
|---------|-----|--------|----|---|------------------|------------------|------|
| 07 - 08 | 178 | 21±0.8 | 13 | 8 | 10 ⁺⁰ | 50 ⁻⁰ | 12.5 |

(3) Q'TY & G.W. Per package

| Code | Inner : Reel | | | Outer : Carton | | |
|------|--------------|-----------|---------|----------------|-----------|--------------|
| | Q'TY (pcs) | G.W. (gw) | Style | Q'TY (pcs) | G.W. (Kg) | Size (cm) |
| B | 2,000 | 170 | 07 - 08 | 100,000 | 9.90 | 42 x 41 x 24 |

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SPECIFICATION FOR APPROVAL

REF. :

| | | | | | |
|------------|--------------------|---------------|------------------|------|---|
| PROD. NAME | SMD Power Inductor | ABC'S DWG NO. | SQ3226□□□□L□-□□□ | | |
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VII . Reliability test :

| Item | Reference documents | Test Condition | Test Specification |
|-------------------------------------|--|---|---|
| 1.High Temperature Exposure | MIL-STD-202 Method 108 | 1.Temperature: 125±2℃ 2.Time:96±2 hours. | 1.No mechanical or electrical damage. 2.Inductance shall not change more than ±10%. |
| 2.Temperature Cycling | JESD22-A 104 | 1.Temperature: -40℃ ~ +125℃ 2.Number of cycle:100 cycle 3.Dwell time:30 minutes | 1.No mechanical or electrical damage. 2.Inductance shall not change more than ±10%. |
| 3.Biased Humidity Test | MIL-STD-202 Method 103 | 1.Temperature : 85±2℃ 2.Humidity: 85% RH. 3.Time:96±2 Hours | 1.No mechanical or electrical damage. 2.Inductance shall not change more than ±10%. |
| 4.Operational Life | JESD22-A 108 | 1.Temperature: 125℃ (Temp. rise included) 2.Time:96±2 hours. 3.Rated current | 1.No mechanical or electrical damage. 2.Inductance shall not change more than ±10%. |
| 5.External Visual | JESD22-B 101 & MIL-STD-883 Method 2009 | Inspect product constructions, marking and workmanship. | 1.No pollution on the surface of products. 2.Clear marking. 3.No crack. |
| 6.Physical Dimensions | JESD22-B 100 | Verify physical dimensions to the applicable product detail specification. | Per product specification standard |
| 7.Resistance to solvents | MIL-STD-202 Method 215 | Immerse into solvent for 3±0.5 minutes & brush 10 times for 3 cycles. | 1.No body change in appearance. 2.No marking blurred. 3.Inductance shall not change more than ±10%. |
| 8.Vibration Test | MIL-STD-202 Method 204 | 1.Frequency and Amplitued : 10-2000-10 Hz, 1.5 mm. 2.Direction:X, Y, Z 3.Test duration:2 hours for each direction, 6 hours in total. | 1.No mechanical or electrical damage. 2.Inductance shall not change more than ±10%. |
| 9.Resistance To Soldering Heat Test | MIL-STD-202 Method 210 & J-STD020D.1 | 1.Highest temperature : 260±5℃. 2.Time (temp. ≥ 217℃) : 60~150 Second. 3.IR reflow times : 3 times. | 1.No mechanical or electrical damage. 2.Inductance shall not change more than ±10%. |
| 10.Saturation Current | JIS C 6436 & User SPEC. | 1.Applied rated current for 5 second. 2.Saturation current | Inductance shall not drop more than 10% typ. |
| 11.Over load | JIS C 6436 & User SPEC. | 1.Applied one and half rated current for a period of 5 minutes. 2.Rated current | No electrical or mechanical damage |
| 12.Temperature Rise Current | JIS C 6436 & User SPEC. | 1.Applied rated current for 10 minutes. 2.Temperature measure by digital surface thermometer. 3.Irms current | Surface temperature rise is less than 20℃ max. |
| 13.Solderability Test | J-STD-002 & JESD22-B 102 | 1.Baking in pre-testing : 150±5℃ / 16Hours±30 min. 2.Peak temperature : 240±5℃ 3.Time (temp. ≥ 217℃) : 60~150 second. 4.IR reflow times : 1 times. | More than 95% soldering coverage min on terminations. |
| 14.Electrical Characteriazation | MIL-STD-202 Method 304 & User SPEC. | 1.Operating temperature : -40℃~125℃ 2.Room temperature : 25℃. | 1.No mechanical or electrical damage. 2.Inductance shall not change more than ±10%. |
| 15.Drop | CNS-C6354 & GB/T 2423.8 | 1.Products shall be mounted on SPEC. PCB and dropped down from a height of 1m 2.Drop total time : 6 time (Every side of sample drop 2 time) | 1. Adhesion on PCB shall be enough. 2. Product appearance shall not break. 3. No electrical damage. |
| 16.Terminal Strength Test | IEC 60068-2-21 | 1.Apply push force to samples mounted on PCB. 2.Force of 1.8 kg for 60±1 seconds. | After test, inductors shall be no mechanical damage. |

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